

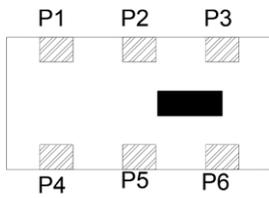
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

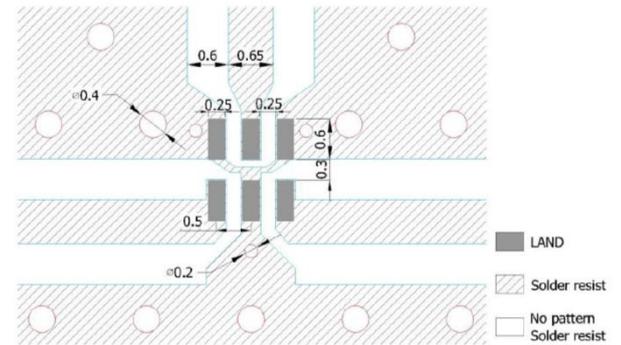
NO.	Specification		
1	Frequency range (MHz)	2400~2500	5170~7125
2	Insertion Loss (dB) @25°C	0.65	1.0
3	Return Loss (dB)	12 min.	10 min.
4	Impedance (Ω)	50	50
5	Attenuation (dB)	2 dB min. @ 3300~4800 MHz	35 dB min. @ 70~108 MHz
		33 dB min. @ 4800~5000 MHz	35 dB min. @ 700~915 MHz
		25 dB min. @ 5170~7125MHz	15 dB min. @ 915~960 MHz
		25 dB min. @ 7200~7500MHz	30 dB min. @ 1425~1470 MHz
		27 dB min. @ 9600~10000MHz	28 dB min. @ 1470~1557 MHz
		20 dB min. @ 12000~12500MHz	26 dB min. @ 1557~1607 MHz
		-	35 dB min. @1710~1785 MHz
		-	26 dB min. @ 1805~1850 MHz
			35 dB min. @ 1850~1910 MHz
			35 dB min. @ 1910~2020 MHz
			23 dB min. @ 2110~2200 MHz
			26 dB min. @ 2300~2400 MHz
			25 dB min. @ 2400~2500 MHz
			20 dB min. @ 2500~2690 MHz
			10 dB min. @ 3400~3800 MHz
	25 dB min. @ 10340~14250 MHz		
	30 dB min. @ 15510~19500 MHz		
	-	22 dB min. @ 19500~21375MHz	
Operating & Storage Condition (Component)			
Operation Temperature Range: -40°C ~ +85°C			
Storage Temperature Range: -40°C~ +85°C			
Storage Condition before Soldering (Included packaging material)			
Storage Temperature Range: +5 ~ +40 °C			
Humidity: 30 to 70% relative humidity			

Construction



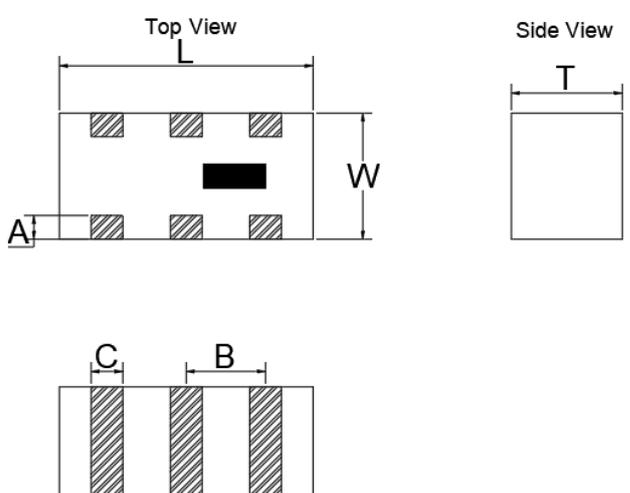
PIN	Connection	PIN	Connection
P1	GND	P4	Low Port
P2	Antenna Input	P5	GND
P3	GND	P6	Higher Port

Mounting Considerations

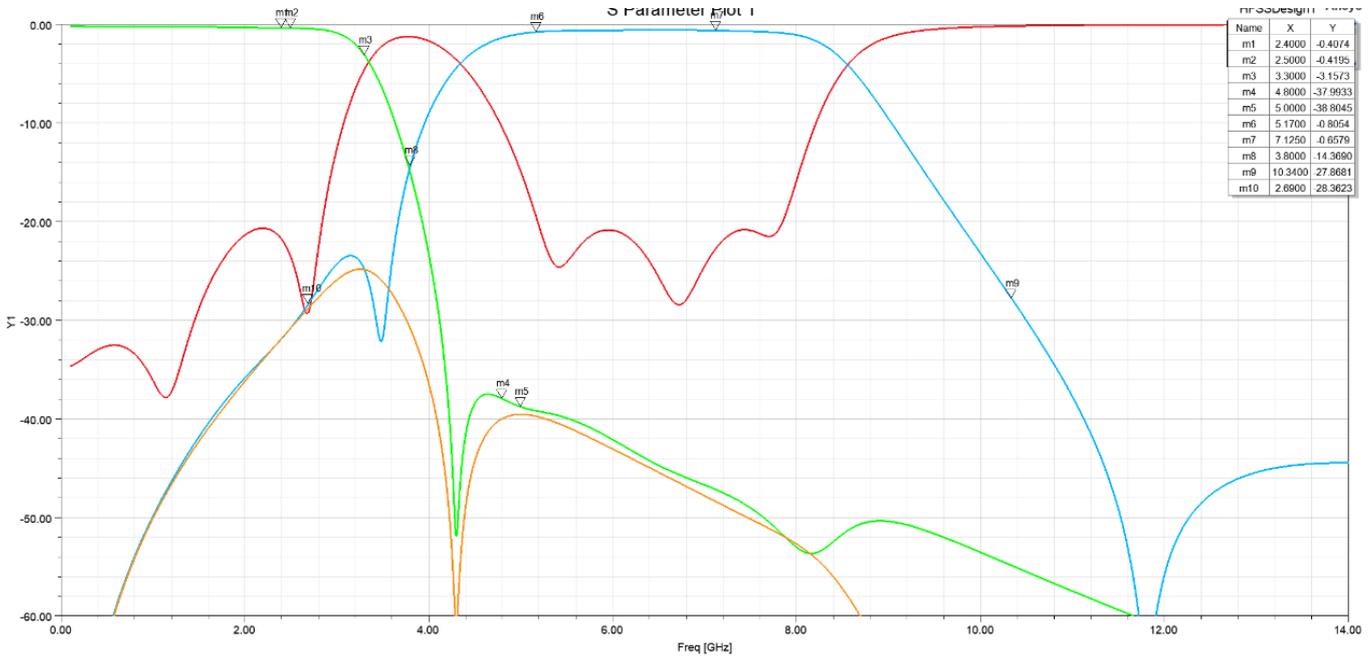


Unit: mm
 Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

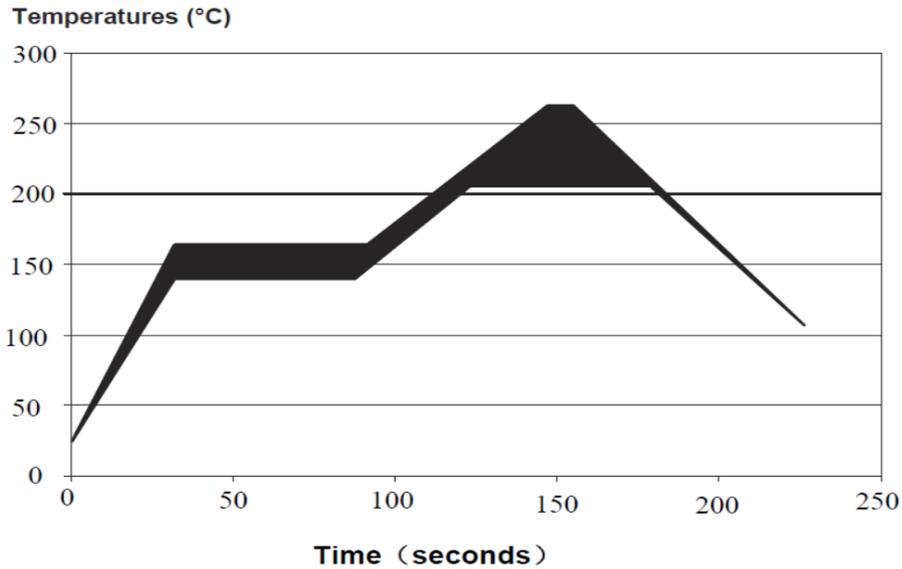
Dimensions

Figure	Symbol	Dimension (mm)
	L	1.6 ± 0.10
	W	0.8 ± 0.10
	T	0.6 ± 0.10
	A	0.15 ± 0.10
	B	0.5 ± 0.10
	C	0.2 ± 0.10

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery)

*Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.